

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Koichi Uchiyama
Serial No. : Unknown
Filed : Herewith
Title : STENCIL SHEET, PROCESS FOR
PRODUCING THE SAME, AND PROCESS FOR
PRODUCING STENCIL PLATE

Attorney Docket : KAW 2 0102

Assistant Commissioner For Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Dear Sir:

Prior to substantive examination of the above-identified patent application, please amend the application as follows:

IN THE CLAIMS:

Please amend claims 3-6, and 9-13 as follows:

3. (Amended) The stencil sheet according to claim 1 wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

4. (Amended) The stencil sheet according to claim 1 wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

5. (Amended) The stencil sheet according to claim 1 wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

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Pamela Stepek
(TYPED OR PRINTED NAME OF SENDER)

(SIGNATURE)

6. (Amended) The stencil sheet according to claim 1 wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

9. (Amended) The process for producing a stencil sheet according to claim 7 wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

10. (Amended) The process for producing a stencil sheet according to claim 7 wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

- (A) a resin having a melting point lower than that of said film
- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

11. (Amended) The process for producing a stencil sheet according to claim 7 wherein said film has an area fraction of the opening portions of said minute perforations in the range of 20 to 70 % and diameters of equivalent circles in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

12. (Amended) The process for producing a stencil sheet according to claim 7 wherein the minute perforations in said film are trapezoidal in vertical cross section.

13. (Amended) The process for producing a stencil sheet according to claim 7 or 8 wherein said film has a thickness in the range of 1.5 to 20 μm .

Please add new claims 15-20 as follows:

15. The stencil sheet according to claim 2 wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

16. The stencil sheet according to claim 2 wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

17. The stencil sheet according to claim 2 wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

18. The stencil sheet according to claim 2 wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

19. The process for producing a stencil sheet according to claim 8 wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

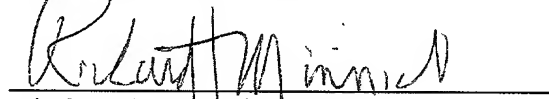
20. The process for producing a stencil sheet according to claim 8 wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

- (A) a resin having a melting point lower than that of said film
- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

REMARKS

It is respectfully submitted that the subject application is now in better condition for examination.

Respectfully submitted,



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VERSION WITH MARKINGS SHOWING CHANGES MADE

3. (Amended) The stencil sheet according to claim 1 [or 2] wherein the area fraction of the opening portions of said minute perforations is in the range of 20 to 70 % and the diameters of equivalent circles are in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

4. (Amended) The stencil sheet according to claim 1 [or 2] wherein said minute perforations in said sheet are trapezoidal in vertical cross section.

5. (Amended) The stencil sheet according to claim 1 [or 2] wherein the thickness of said sheet is in the range of 1.5 to 20 μm .

6. (Amended) The stencil sheet according to claim 1 [or 2] wherein said stencil sheet further comprises a porous support laminated on one side of said sheet.

9. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein the process further comprises laminating a porous support on one side of said film after a roller having drill-like projections formed on its surface was pressed against said film of a synthetic resin to form minute perforations and said minute perforations were filled with said filler or resin.

10. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein said filler or resin is selected from the group consisting of the following resins (A), (B), and (C).

(A) a resin having a melting point lower than that of said film

- (B) a resin which is soluble in a solvent
- (C) a heat adhesive resin

11. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein said film has an area fraction of the opening portions of said minute perforations in the range of 20 to 70 % and diameters of equivalent circles in the range of 5 to 200 μm when the opening portions are assumed to be circular in shape.

12. (Amended) The process for producing a stencil sheet according to claim 7 [or 8] wherein the minute perforations in said film are trapezoidal in vertical cross section.

13. (Amended) The process for producing a stencil sheet according to claim 7 or 8 wherein said film has a thickness in the range of 1.5 to 20 μm .